

# 4V Drive Nch MOSFET

## RHU002N06

### ●Structure

Silicon N-channel  
MOSFET transistor

### ●Features

- 1) Low on-resistance.
- 2) High ESD.
- 3) High-speed switching.
- 4) Low-voltage drive (4V).
- 5) Drive circuits can be simple.
- 6) Parallel use is easy.

### ●Applications

Switching

### ●Packaging specifications

Type	Package	Taping
	Code	T106
	Basic ordering unit (pieces)	3000
RHU002N06		○

### ●Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit	
Drain-source voltage	V <sub>DS</sub>	60	V	
Gate-source voltage	V <sub>GS</sub>	±20	V	
Drain current	Continuous	I <sub>D</sub>	±200	mA
	Pulsed	I <sub>DP</sub> *1	±800	mA
Source current (Body diode)	Continuous	I <sub>S</sub>	200	mA
	Pulsed	I <sub>SP</sub> *1	800	mA
Total power dissipation	P <sub>D</sub> *2	200	mW	
Channel temperature	T <sub>ch</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

\*1 P<sub>w</sub>≤10μs, Duty cycle≤1%

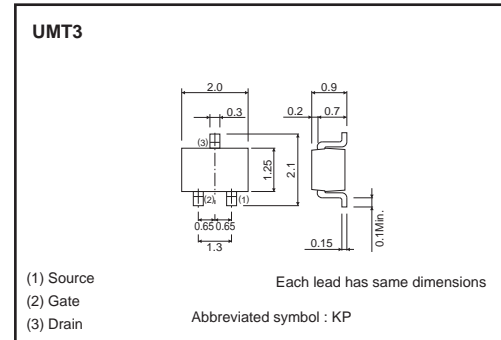
\*2 Each terminal mounted on a recommended

### ●Thermal resistance

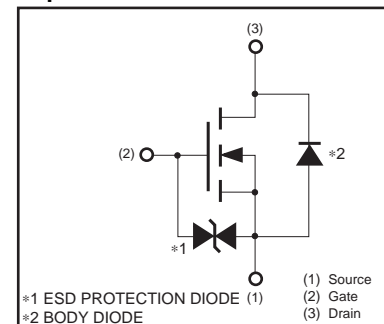
Parameter	Symbol	Limits	Unit
Channel to ambient	R <sub>th</sub> (ch-a) *	625	°C / W

\* With each pin mounted on the recommended land.

### ●Dimensions (Unit : mm)



### ●Equivalent circuit



\* A protection diode has been built in between the gate and the source to protect against static electricity when the product is in use. Use the protection circuit when fixed voltages are exceeded.

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Gate leakage current	I <sub>GSS</sub>	-	-	±10	μA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	60	-	-	V	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V
Drain cutoff current	I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS(th)</sub>	1	-	2.5	V	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA
Drain-source on-state resistance	R <sub>DS(on)*</sub>	-	1.7	2.4	Ω	I <sub>D</sub> =200mA, V <sub>GS</sub> =10V
		-	2.8	4.0		I <sub>D</sub> =200mA, V <sub>GS</sub> =4V
Forward transfer admittance	Y <sub>fs</sub>  *	0.1	-	-	S	V <sub>DS</sub> =10V, I <sub>D</sub> =200mA
Input capacitance	C <sub>iss</sub>	-	15	-	pF	V <sub>DS</sub> =10V
Output capacitance	C <sub>oss</sub>	-	8	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	-	4	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)*</sub>	-	6	-	ns	I <sub>D</sub> =100mA, V <sub>DD</sub> =30V
Rise time	t <sub>r</sub> *	-	5	-	ns	V <sub>GS</sub> =10V
Turn-off delay time	t <sub>d(off)*</sub>	-	12	-	ns	R <sub>L</sub> =300Ω
Fall time	t <sub>f</sub> *	-	95	-	ns	R <sub>G</sub> =10Ω
Total gate charge	Q <sub>g</sub> *	-	2.2	4.4	nC	V <sub>DD</sub> =30V
Gate-source charge	Q <sub>gs</sub> *	-	0.6	-	nC	V <sub>GS</sub> =10V
Gate-drain charge	Q <sub>gd</sub> *	-	0.3	-	nC	I <sub>D</sub> =200mA

\* Pulsed

●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub> *	-	-	1.2	V	I <sub>S</sub> =200mA, V <sub>GS</sub> =0V

\*Pulsed

●Electrical characteristic curves

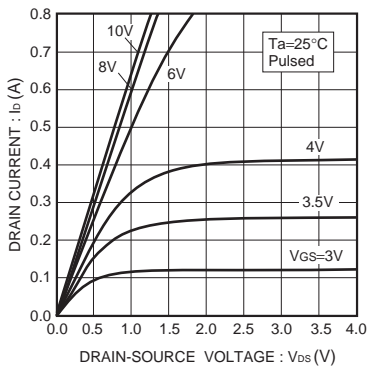


Fig.1 Typical Output Characteristics

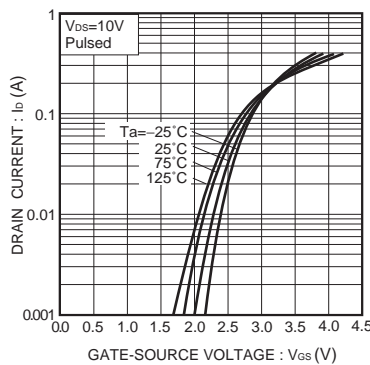


Fig.2 Typical Transfer Characteristics

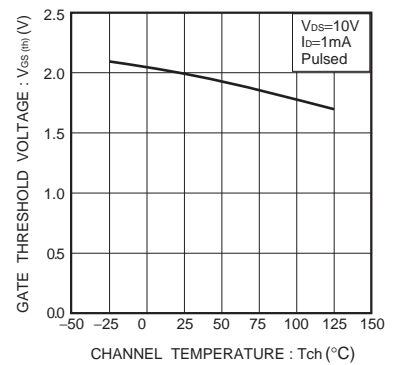


Fig.3 Gate Threshold Voltage vs. Channel Temperature

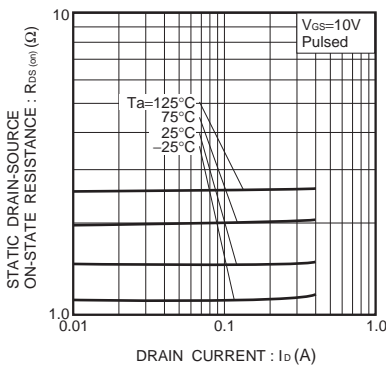


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current ( I )

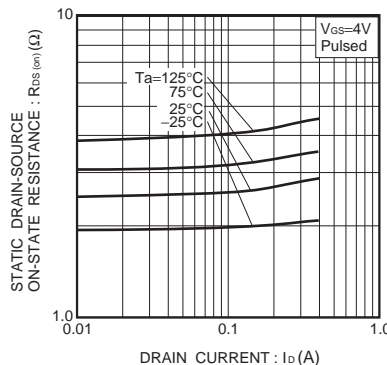


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current ( II )

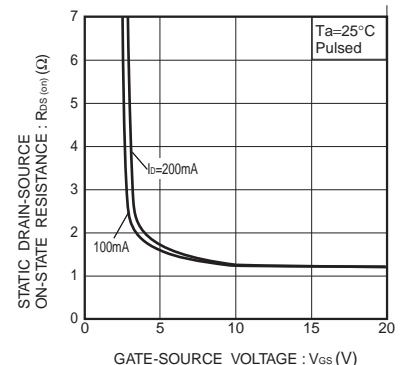


Fig.6 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

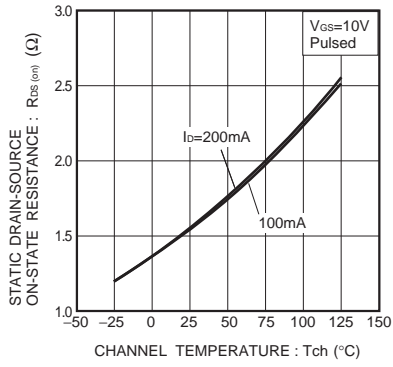


Fig.7 Static Drain-Source On-State Resistance vs. Channel Temperature

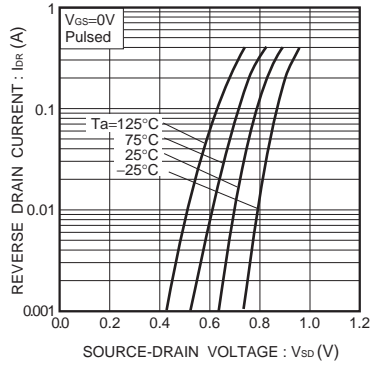


Fig.8 Reverse Drain Current vs. Source-Drain Voltage ( I )

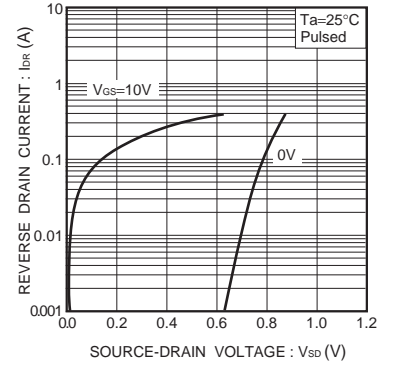


Fig.9 Reverse Drain Current vs. Source-Drain Voltage ( II )

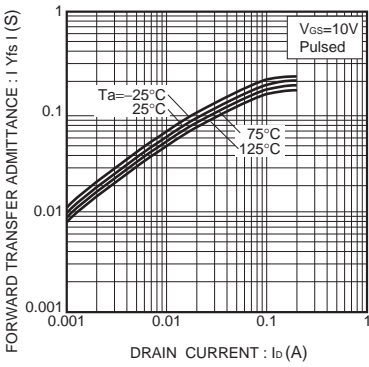


Fig.10 Forward Transfer Admittance vs. Drain Current

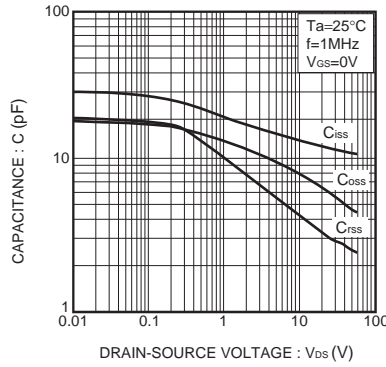


Fig.11 Typical Capacitance vs. Drain-Source Voltage

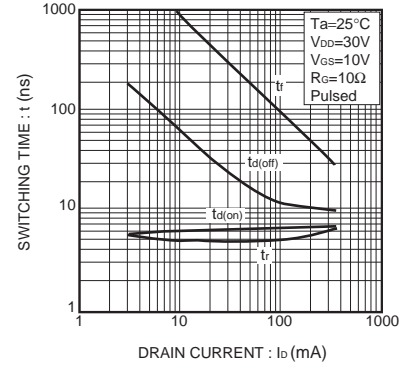


Fig.12 Switching Characteristics

●Switching characteristics measurement circuit

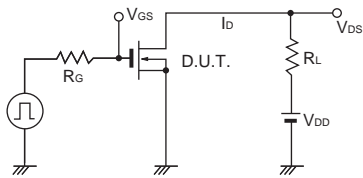


Fig.13 Switching time test circuit

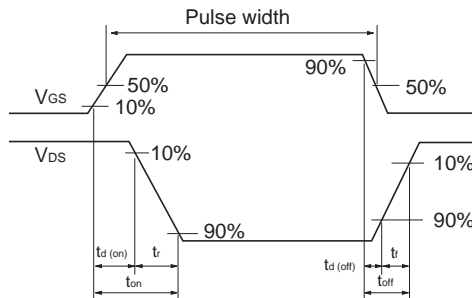


Fig.14 Switching time waveforms

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